



April 2000

QFET™

FQD4N20 / FQU4N20

200V N-Channel MOSFET

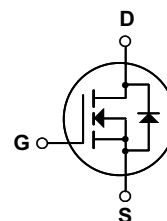
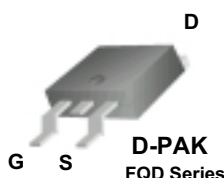
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply, DC-AC converters for uninterrupted power supply, motor control.

Features

- 3.0A, 200V, $R_{DS(on)} = 1.4\Omega @ V_{GS} = 10V$
- Low gate charge (typical 5.0 nC)
- Low C_{rss} (typical 5.0 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQD4N20 / FQU4N20	Units
V_{DSS}	Drain-Source Voltage	200	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	3.0	A
	- Continuous ($T_C = 100^\circ\text{C}$)	1.95	A
I_{DM}	Drain Current - Pulsed (Note 1)	12	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	52	mJ
I_{AR}	Avalanche Current (Note 1)	3.0	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	3.0	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5	V/ns
P_D	Power Dissipation ($T_A = 25^\circ\text{C}$) *	2.5	W
	Power Dissipation ($T_C = 25^\circ\text{C}$)	30	W
	- Derate above 25°C	0.24	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	4.17	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *	--	50	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	110	$^\circ\text{C}/\text{W}$

* When mounted on the minimum pad size recommended (PCB Mount)

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	200	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	--	0.24	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 160\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.0	--	5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 1.5\text{ A}$	--	1.12	1.4	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 40\text{ V}, I_D = 1.5\text{ A}$ (Note 4)	--	1.85	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	170	220	pF
C_{oss}	Output Capacitance		--	35	45	pF
C_{rss}	Reverse Transfer Capacitance		--	5	7	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 100\text{ V}, I_D = 3.6\text{ A},$ $R_G = 25\text{ }\Omega$ (Note 4, 5)	--	7	25	ns
t_r	Turn-On Rise Time		--	50	110	ns
$t_{d(off)}$	Turn-Off Delay Time		--	7	25	ns
t_f	Turn-Off Fall Time		--	25	60	ns
Q_g	Total Gate Charge	$V_{DS} = 160\text{ V}, I_D = 3.6\text{ A},$ $V_{GS} = 10\text{ V}$ (Note 4, 5)	--	5.0	6.5	nC
Q_{gs}	Gate-Source Charge		--	1.4	--	nC
Q_{gd}	Gate-Drain Charge		--	2.1	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	3.0	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	12	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 3.0 A	--	--	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 3.6 A,	--	90	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs (Note 4)	--	0.24	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 8.7\text{ mH}, I_{AS} = 3.0\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 3.6\text{ A}, dI/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

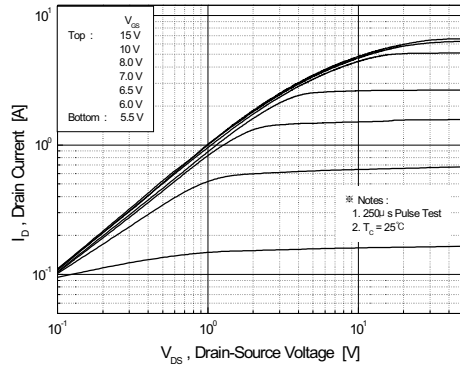


Figure 1. On-Region Characteristics

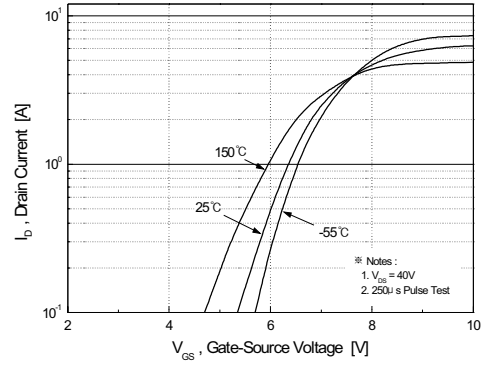


Figure 2. Transfer Characteristics

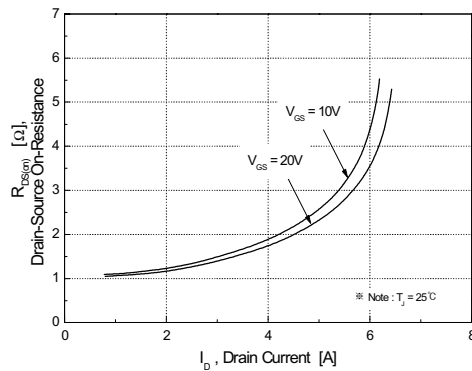


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

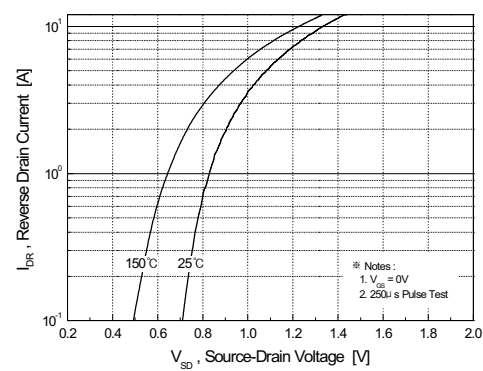


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

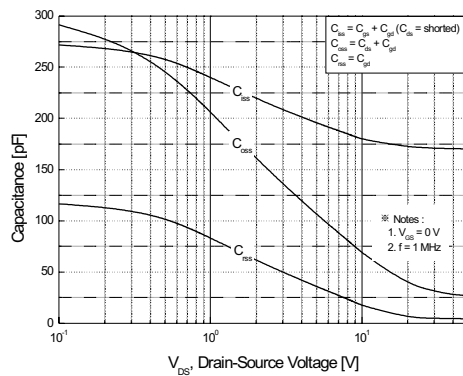


Figure 5. Capacitance Characteristics

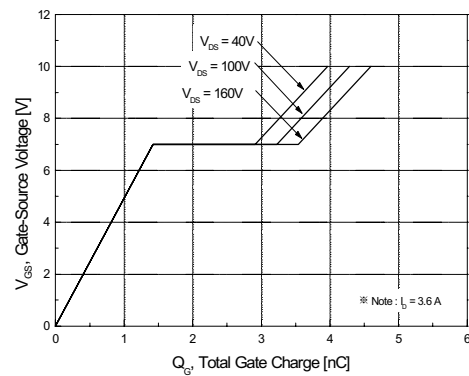


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

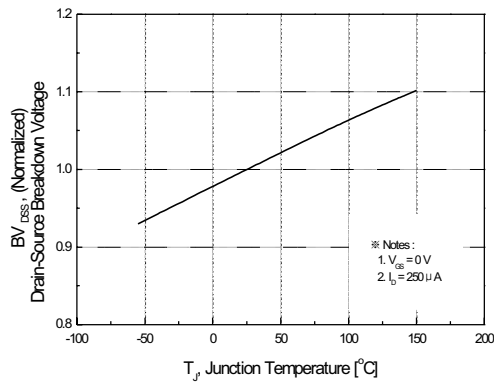


Figure 7. Breakdown Voltage Variation vs. Temperature

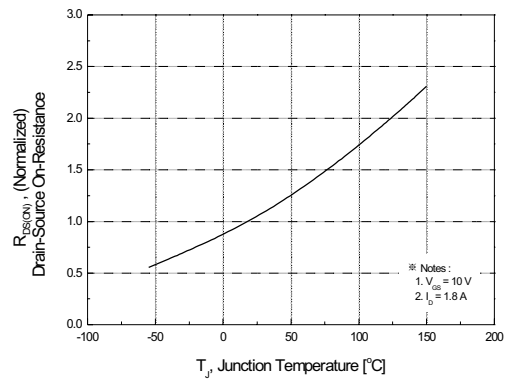


Figure 8. On-Resistance Variation vs. Temperature

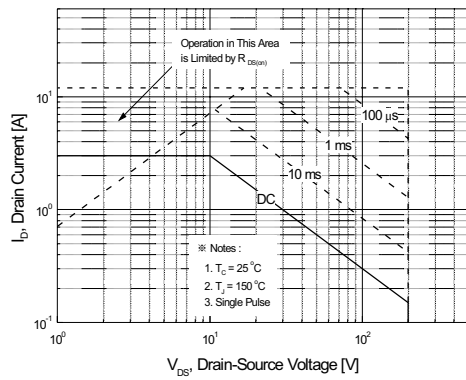


Figure 9. Maximum Safe Operating Area

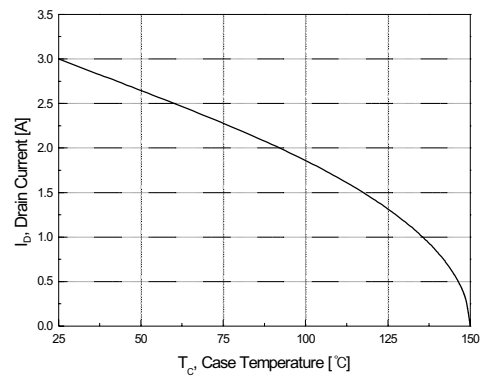


Figure 10. Maximum Drain Current vs. Case Temperature

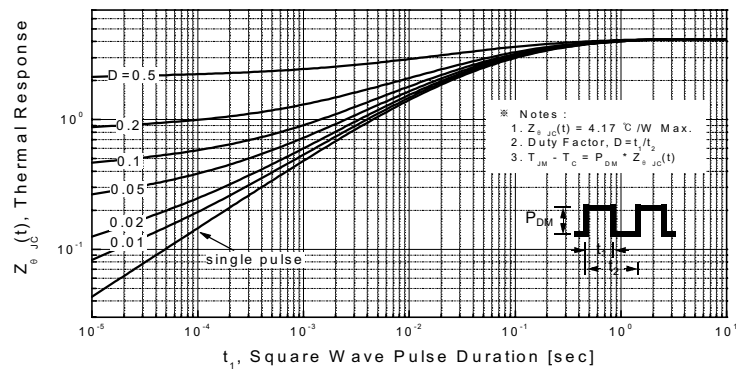


Figure 11. Transient Thermal Response Curve

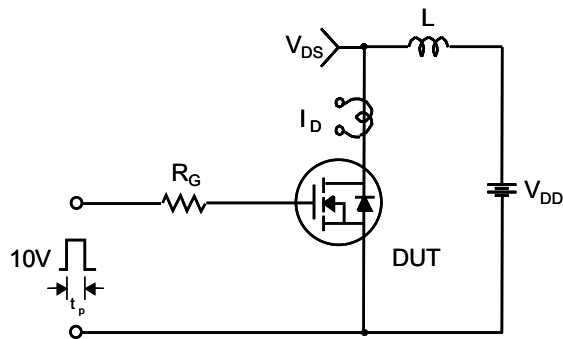
Gate Charge Test Circuit & Waveform



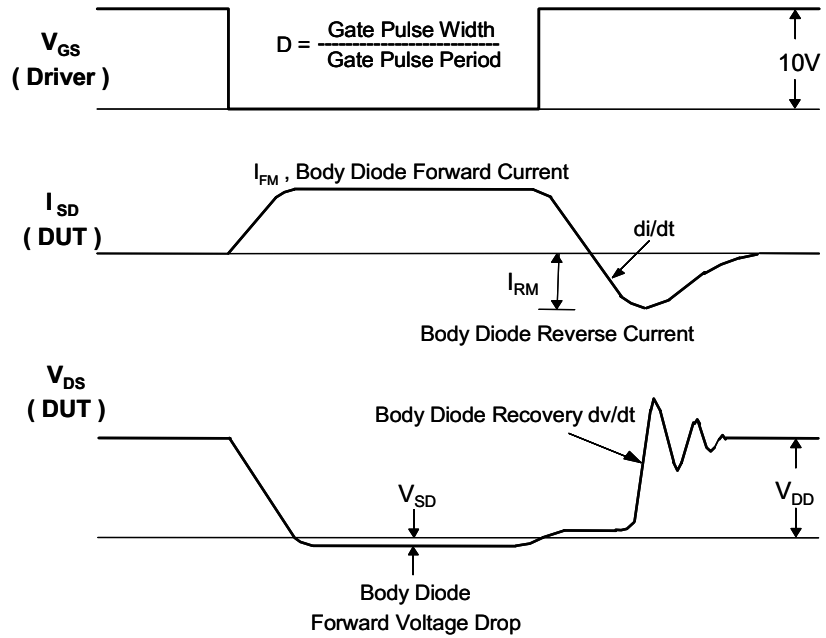
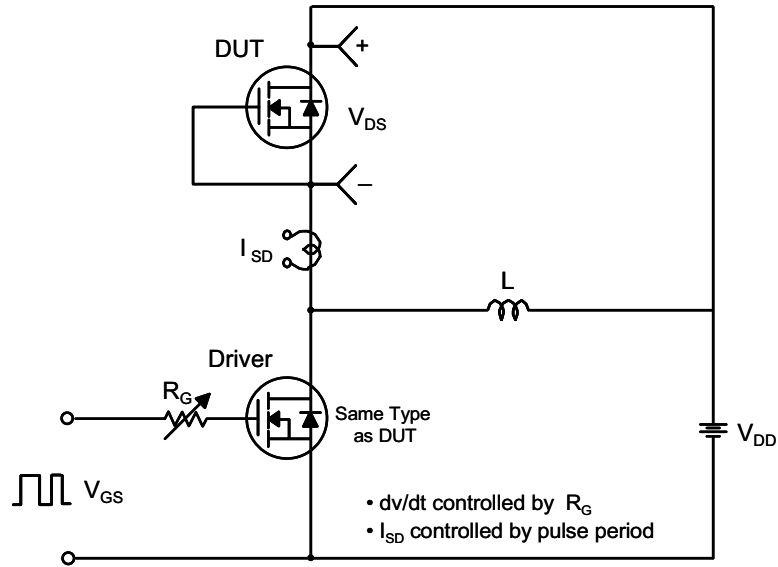
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



Technical drawing of a 12-pin D-sub connector showing front, side, and top views with dimensions in millimeters.

Front View Dimensions:

- Overall width: 6.60 ± 0.20
- Pin pitch (center-to-center): 5.34 ± 0.30
- Pin width: 0.76 ± 0.10
- Pin spacing (edge to center): 0.89 ± 0.10
- Pin height: 0.91 ± 0.10
- Pin thickness: 0.50 ± 0.10
- Pin length: 2.30 ± 0.20
- Pin diameter: $\phi 0.50$
- Pin hole diameter: $\phi 0.40$
- Pin hole depth: 0.10
- Pin hole position: $(2 \times R0.25)$
- Pin hole diameter: $\phi 0.40$
- Pin hole depth: 0.10
- Pin hole position: $(2 \times R0.25)$
- Pin hole diameter: $\phi 0.40$
- Pin hole depth: 0.10
- Pin hole position: $(2 \times R0.25)$

Side View Dimensions:

- Overall height: 9.50 ± 0.30
- Pin height: 0.91 ± 0.10
- Pin thickness: 0.50 ± 0.10
- Pin length: 2.30 ± 0.20
- Pin diameter: $\phi 0.50$
- Pin hole diameter: $\phi 0.40$
- Pin hole depth: 0.10
- Pin hole position: $(2 \times R0.25)$
- Pin hole diameter: $\phi 0.40$
- Pin hole depth: 0.10
- Pin hole position: $(2 \times R0.25)$

Top View Dimensions:

- Overall width: 6.60 ± 0.20
- Pin pitch (center-to-center): 5.34 ± 0.30
- Pin width: 0.76 ± 0.10
- Pin spacing (edge to center): 0.89 ± 0.10
- Pin height: 0.91 ± 0.10
- Pin thickness: 0.50 ± 0.10
- Pin length: 2.30 ± 0.20
- Pin diameter: $\phi 0.50$
- Pin hole diameter: $\phi 0.40$
- Pin hole depth: 0.10
- Pin hole position: $(2 \times R0.25)$
- Pin hole diameter: $\phi 0.40$
- Pin hole depth: 0.10
- Pin hole position: $(2 \times R0.25)$

Package Dimensions (Continued)

IPAK



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